

Title (en)

METHOD FOR THE PRODUCTION OF A MEMORY CELL AND STRUCTURE THEREOF

Title (de)

VERFAHREN ZUR HERSTELLUNG UND AUFBAU EINER SPEICHERZELLE

Title (fr)

PROCEDE DE PRODUCTION ET STRUCTURE D'UNE CELLULE DE MEMOIRE

Publication

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Application

EP 03704257 A 20030127

Priority

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Abstract (en)

[origin: US2003148582A1] The memory cell has a source region and a drain region in semiconductor material and, above a channel region between the source and drain regions, a three-layered layer structure with a storage layer between boundary layers and a gate electrode arranged thereon. The storage layer is replaced above the channel region by an etching layer made of Al₂O₃. During fabrication, the etching layer is etched out laterally and the second boundary layer is thus undercut. The resulting interspaces are filled with the material of the storage layer. The provision of suitable spacers makes it possible to define the dimensions of the memory cell.

IPC 1-7

H01L 21/28; H01L 29/788

IPC 8 full level

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